SDK-E3G-FANOUT-R1: Evaluation/Carrier Board for the Enabler III Family of Modules

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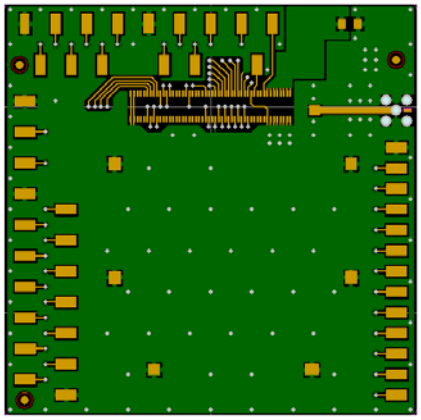

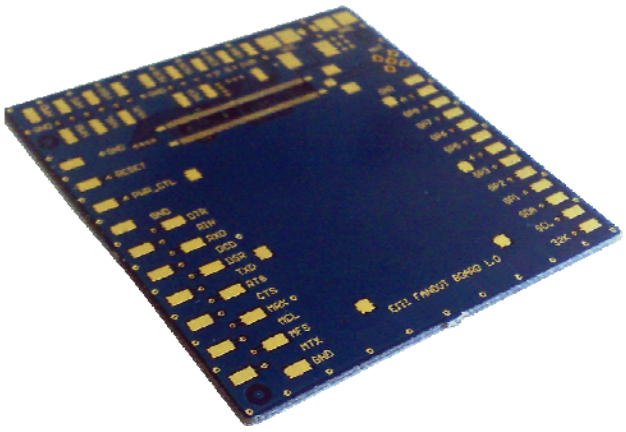

A low-cost, RoHS compliant, flexible evaluation/carrier board for use with Enabler IIIG modules **with integral SIM holder** (GSM0308-X1 & EDG0308-X1 – Module sold separately). This board allows for quick integration of the module via SMT pads connected to the 100-way Molex connector mounted on the PCB.

SPECIFICATIONS

Size:	50 x 50 mm
Power:	3.4V–4.4V DC (please see Enfora Integration Guide)

Connections:

Power	VBATT, VBAK & VREF1V8
Power Control	PWR_CTL & Reset with accompanying GND pads
Serial Interface	Full 9 signal 1V8 logic level serial interface
General Purpose I/0	GPIO 1-8 including ADC
Audio (Analog)	Access to handset & headset interface
Audio (Digital)	Access to Ti CODEC
RF (Module Option –71)	MCD connectivity (Cable sold separately)
RF (Module Option –11)	MMCX connector (Connector sold separately)

Molex 51338-1074:	100-Way Board Mounted Connector to suit Enabler III modules

Part Numbers:

SDK-E3G-FANOUT-R1	Populated with all parts except module and MMCX
SDK-E3G-FANOUT-R1/U	Unpopulated Board

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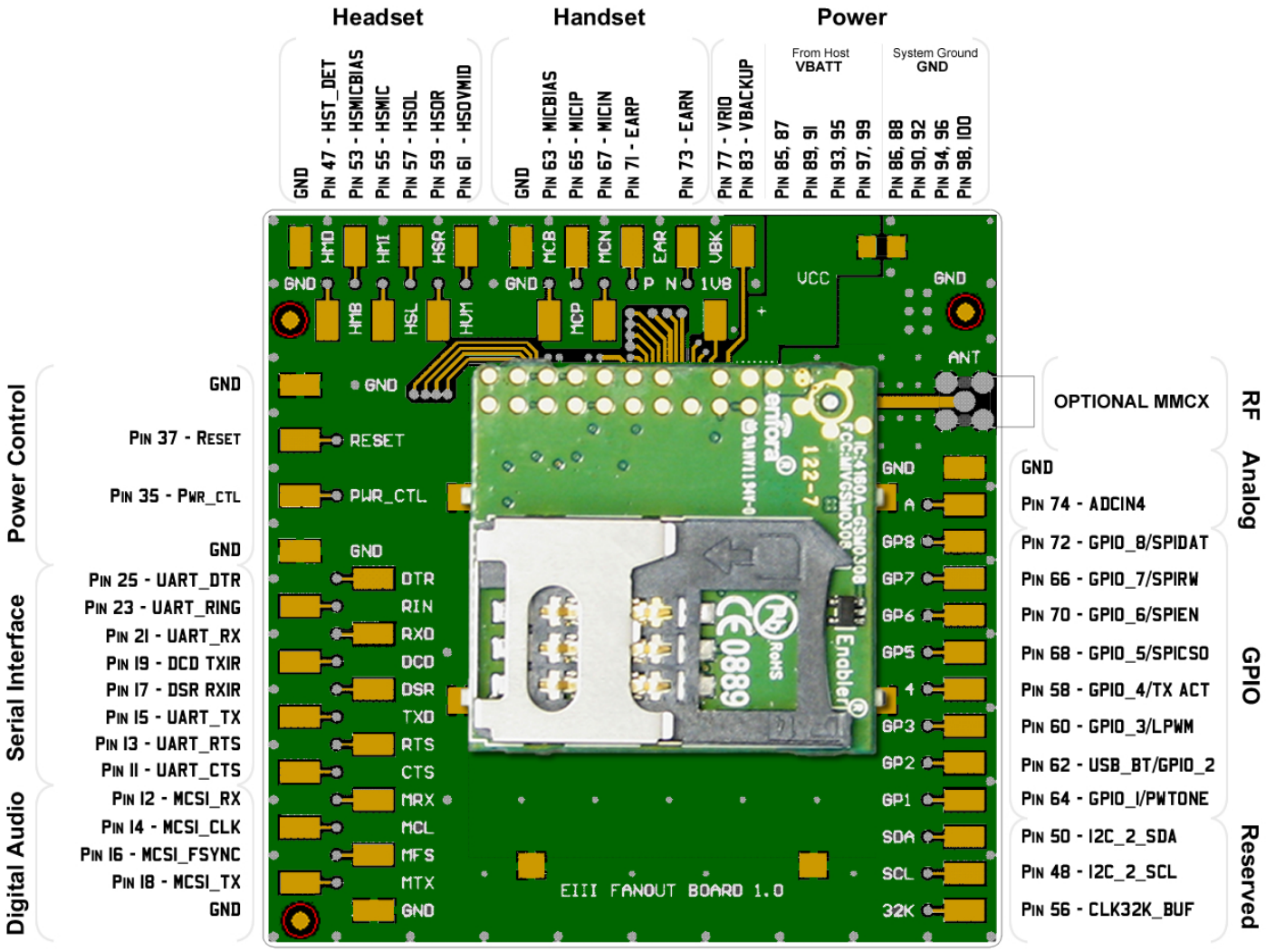
PIN LAYOUT

Please use this Evaluation Board in reference to the Enfora Integrator Guide when considering Power Supply, Signal Conditioning and Connectivity.

The description below refers to pin numbers on the Molex 100 way connector, described on page 1.



Note:
These Pin numbers refer to the Molex 100-pin connector, with descriptions based on the Enabler III Integrator Guide: Revision 1.03. The serial interface is described relative to a DTE. These functionality descriptions may be subject to change. For more info contact sales@3rdplatform.com

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